

07-27-1998



100776278

U.S. PATENT AND TRADEMARK OFFICE

JC549 U.S. PTO

09/118065



Case Docket No. <u>980850</u>	U.S. DEPARTMENT OF COMMERCE Patent and Trademark Office
RECORDATION FORM COVER SHEET PATENTS ONLY	
7-17-98 To the Assistant Commissioner for Patents. Please record the attached original documents or copy thereof.	
1. Name of conveying parties: Hiroyuki HIRATA, Yuuichi KOMIZO, Yasuto FUKADA and Masakatsu UEDA Additional name(s) of conveying party(ies) attached? Yes No <u>XX</u>	
2. Name and address of receiving party: Name: SUMITOMO METAL INDUSTRIES, LTD. Street Address: <u>5-33, Kitahama 4-chome, chuo-ku,</u> <u>Osaka-shi, Osaka 541 Japan</u> Additional name(s) & address(es) attached? Yes No <u>XX</u>	
3. Nature of conveyance: <u>Assignment</u> 09 118065 Execution Dates: June 5, 1998, June 8, 1998, June 18, 1998 and June 11, 1998	
4. Title: METHOD FOR BONDING DUAL-PHASE STAINLESS STEEL	
5. Application number(s) or patent number(s): If this document is being filed together with a new application, the execution dates of the application are: <u>June 5, 1998, June 8, 1998, June 18, 1998 and June 11, 1998</u> Additional numbers attached? Yes No <u>XX</u>	

07/22/1998 HULLARI 00000073 09118065

02 FC:581

40.00 BP

PATENT
REEL: 9332 FRAME: 0395

6. Name and address of party to whom correspondence concerning document should be mailed:

Name: Armstrong, Westerman, Hattori,
McLeland & Naughton
Suite 1000
1725 K Street, N.W.
Washington, D.C. 20006

7. Total number of applications and patents involved: 1

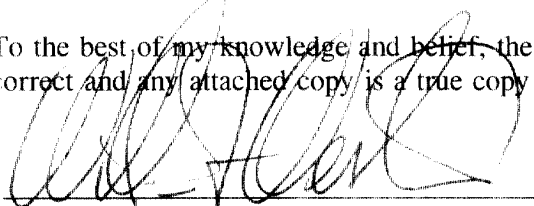
8. Total fee (37 CFR 3.41). \$ **40.00**

XX Check enclosed

9. Deposit Account No.: **01-2340**

10. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.



William F. Westerman
Reg. No.: 29,988

Date July 17, 1998

Total number of pages including cover sheet: 3

WFW/tmb

U.S. ASSIGNMENT

IN CONSIDERATION of the sum of One Dollar (\$1.00), and of other good and valuable consideration paid to the undersigned inventor(s) (hereinafter ASSIGNOR) by

(Insert ASSIGNEE's
Name(s) Address(es))

SUMITOMO METAL INDUSTRIES, LTD.
5-33, Kitahama 4-chome, chuo-ku, Osaka-shi, Osaka 541 Japan
(hereinafter ASSIGNEE), the receipt of which is hereby acknowledged, the undersigned ASSIGNOR hereby sells, assigns and transfers to ASSIGNEE the entire and exclusive right, title and interest to the invention entitled

(Title of Invention)

Method for Bonding Dual-Phase Stainless Steel

(*If the assignment is
being filed after the
filing of the application,
this section must be
completed)

for which application for Letters Patent of the United States was executed on even date herewith unless otherwise indicated below:

*filed on _____, Serial No. _____
(Armstrong, Westerman, Hattori, McLeland & Naughton is hereby authorized to insert the series code, serial number and/or filing date hereon, when known)

and all Letters Patent of the United States to be obtained therefor on said application or any continuation, divisional, substitute, reissue or reexamination thereof for the full term or terms for which the same may be granted.

The ASSIGNOR agrees to execute all papers necessary in connection with the application and any continuation, divisional, reissue or reexamination applications thereof and also to execute separate assignments in connection with such applications as the ASSIGNEE may deem necessary or expedient.

The ASSIGNOR agrees to execute all papers necessary in connection with any interference, litigation, or other legal proceeding which may be declared concerning this application or any continuation, divisional, reissue or reexamination thereof or Letters Patent or reissue patent issued thereon and to cooperate with the ASSIGNEE in every way possible in obtaining and producing evidence and proceeding with such interference, litigation, or other legal proceeding.

IN WITNESS WHEREOF, the undersigned inventor(s) has(have) affixed his/her/their signature(s).

(Signatures)

<u>Hiroiyuki Hirata</u> (SIGNATURE)	Hiroiyuki Hirata (TYPE NAME)	<u>June 5th, 1998</u> (DATE)
<u>Yuuichi Komizo</u> (SIGNATURE)	Yuuichi Komizo (TYPE NAME)	<u>June 8th, 1998</u> (DATE)
<u>Yasuto Fukada</u> (SIGNATURE)	Yasuto Fukada (TYPE NAME)	<u>June 15, 1998</u> (DATE)
<u>Masakatsu Ueda</u> (SIGNATURE)	Masakatsu Ueda (TYPE NAME)	<u>June 11, 1998</u> (DATE)
_____ (SIGNATURE)	_____ (TYPE NAME)	_____ (DATE)
_____ (SIGNATURE)	_____ (TYPE NAME)	_____ (DATE)
_____ (SIGNATURE)	_____ (TYPE NAME)	_____ (DATE)

NO LEGALIZATION REQUIRED